

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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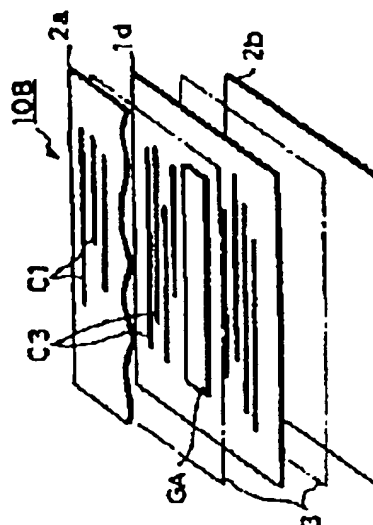
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APPLICANT : MITSUBISHI ELECTRIC CORP;

INVENTOR : OTA MAKOTO;

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TITLE : PRINTED CIRCUIT BOARD



**ABSTRACT :** PURPOSE: To improve a wiring efficiency and to reduce the number of layers of a printed circuit board by increasing thicknesses of a copper layers of a ground pattern and a power source pattern to concentrate to reduce its area, and providing a signal circuit pattern together in a vacant space.

CONSTITUTION: A copper foil having a thickness of about 70-170 $\mu$ m is used as an inner layer board 1d, its sectional area is set to equal to or more than prior art, and a ground pattern GA in which its area is reduced to half or less, is provided. Then, a signal circuit pattern C3 is provided together near the pattern GA in a vacant space of the board 1d. Thus, the circuit pattern can be largely increased in the same space, thereby enhancing a density of wirings.

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